L Number	Hits	Search Text	DB	Time stamp
1~	0	duplxer same advan\$4	USPAT; EPO; JPO; DERWENT;	2003/12/13 15:55
3	4	(duplexer same advan\$4) and (wireless adj system)	USOCR USPAT; EPO; JPO; DERWENT;	2003/12/13 15:56
2	448	duplexer same advan\$4	USOCR USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:03
4	2	("5578525").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:08
5	14	("4233620"   "4264917"   "4633573"   "4721945"   "4769272"   "4835120"   "4901136"   "5102829"   "5206188"   "5309021"   "5342807"   "5357400"   "5474957"   "5519936").PN.	USPAT	2003/12/13 16:04
6	23	5578525.URPN.	USPAT	2003/12/13 16:09
7	0	(437/206).CCLS.	USPAT; EPO; JPO; DERWENT;	2003/12/13 16:08
8	0	(437/206).CCLS.	USOCR USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:09
9	1021	(257/704).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:24
10	8859	solder adj ball	USPAT; EPO; JPO; DERWENT;	2003/12/13 16:28
11	8437	solder adj paste	USOCR USPAT; EPO; JPO; DERWENT;	2003/12/13 16:28
12	1033	(solder adj ball) and (solder adj paste)	USOCR USPAT; EPO; JPO; DERWENT;	2003/12/13 17:34
13	167195	PCB or (printed adj circuit adj board)	USOCR USPAT; EPO; JPO; DERWENT;	2003/12/13 16:30
14	3525645	(PCB or (printed adj circuit adj board)) ad opening	USOCR USPAT; EPO; JPO; DERWENT;	2003/12/13 16:30
15	167195	(PCB or (printed adj circuit adj board)) and ((PCB or (printed adj circuit adj board)) ad opening)	USOCR USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
16	697	((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
17	245	(((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)) and carrier	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:41

18	1983	signal adj trace	USPAT;	2003/12/13 16:42
•			EPO; JPO;	
			DERWENT;	
			USOCR	
19	834	signal adj skew	USPAT;	2003/12/13 16:42
		organia auj onov	EPO; JPO;	2003/12/13 10.42
			DERWENT:	
			,	
20	7	(signal adj trace) and (signal adj skew)	USOCR USPAT;	00004040404045
	•	(Signal adj ti ace) and (Signal adj Skew)		2003/12/13 16:45
			EPO; JPO;	
			DERWENT;	
21	2	("5983493"   "6194778").PN.	USOCR	0000140140 40 44
22	138656		USPAT	2003/12/13 16:44
22	130030	multilayer	USPAT;	2003/12/13 16:45
			EPO; JPO;	
			DERWENT;	
	0040		USOCR	
23	3048	multilayer adj substrate	USPAT;	2003/12/13 16:46
			EPO; JPO;	
			DERWENT;	
	_		USOCR	
24	2	(multilayer adj substrate) and (signal adj skew)	USPAT;	2003/12/13 16:47
			EPO; JPO;	
			DERWENT;	
			USOCR	
25	16	multilayer and (signal adj skew)	USPAT;	2003/12/13 16:47
			EPO; JPO;	
			DERWENT;	
			USOCR	
26	32	("3930857"   "4604644"   "4814943"   "5121190"	USPAT	2003/12/13 16:55
		"5128746"   "5136365"   "5194930"   "5216278"		
		"5218234"   "5227008"   "5261155"   "5355283"		
		"5357673"   "5371404"   "5398863"   "5401913"		
		"5436503"   "5442240"   "5450283"   "5489749"		
		"5536909"   "5550408"   "5583376"   "5583378"		
		"5601678"   "5647123"   "5650593"   "5663530"		
		"5686703"   "5717252"   "5744863"   "5801449").PN.		
27	155	((solder adj ball) and (solder adj paste)) and (melting adj	USPAT:	2003/12/13 17:34
		temperature)	EPO; JPO;	2000/12/10 11:04
		,,	DERWENT;	
			USOCR	
28	16	174/250-268.ccls. and (((solder adj ball) and (solder adj	USPAT;	2003/12/13 17:37
20		paste)) and (melting adj temperature))	EPO; JPO;	2003/12/13 17:37
		paste)) and (meiting adjitemperature))		
	İ		DERWENT;	
29	17	361/760-795.ccls. and (((solder adj ball) and (solder adj	USOCR	00004040404767
	''	paste)) and (melting adj temperature))	USPAT;	2003/12/13 17:37
		paste)) and (meiting adjitemperature))	EPO; JPO;	
			DERWENT;	
30	12	/"A992A5A"   "5072075"   "5404400"   "5400404"	USOCR	
30	12	("4882454"   "5072075"   "5121190"   "5483421"     "5574630"   "5645087"   "5664080"   "5708563"	USPAT	2003/12/13 17:37
		"5574630"   "5615087"   "5661089"   "5798563"   "5894173"   "5900675"   "5926377"   "5982630").PN.		
			1	i